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**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1. (Currently Amended) A semiconductor module comprising:
  - a semiconductor device provided with a semiconductor chip; and
  - a conductive cover for electromagnetic shielding bonded to the semiconductor device via an adhesive coat;
  - wherein the conductive cover includes a surface facing the adhesive coat, the surface being formed with a convex portion protruding toward the adhesive coat[[.]];
  - wherein around the convex portion, a space is formed for filling in adhesive to form the adhesive coat[[.]];
  - wherein the semiconductor device includes a surface facing the adhesive coat, the surface being formed with a recess; and
  - wherein at least a part of the convex portion is positioned on a portion other than the recess.
2. (Original) The semiconductor module according to claim 1, comprising three or more convex portions arranged nonlinearly.
3. (Original) The semiconductor module according to claim 1, comprising two or more elongated convex portions having center axes non-collinear to each other.
4. (Canceled)
5. (Previously Presented) The semiconductor module according to claim 1, wherein the conductive cover is made of a metal, and the convex portion is formed by embossing.
6. (Previously Presented) The semiconductor module according to claim 1,

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wherein the semiconductor device includes a light emitting element capable of generating infrared rays, a light receiving element capable of receiving and detecting infrared rays, and an IC chip,

wherein the semiconductor module is an infrared communication module capable of transmitting and receiving infrared rays.

7. (Currently Amended) A semiconductor module comprising:

a semiconductor device provided with a semiconductor chip; and

a conductive cover for electromagnetic shielding bonded to the semiconductor device via an adhesive coat;

wherein the semiconductor device includes a surface facing the adhesive coat, the surface being formed with a convex portion protruding toward the adhesive coat,

wherein around the convex portion, a space is formed for filling in adhesive to form the adhesive coat[.];

wherein the semiconductor device includes a surface facing the adhesive coat, the surface being formed with a recess; and

wherein at least a part of the convex portion is positioned on a portion other than the recess.